MBR1035F THRU MBR10150F Schottky Diodes

Features

High efficiency operation

RLILAN

- Guard ring for enhanced ruggedness and long term . reliablity
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Solder dip maximum peak of 275 °C /7s, per JESD 22-B106

Typical Application

For use in switching power supplies, converters, freewheeling diodes and reverse battery protection.

Mechanical Data

- Package: ITO-220AC Molding compound meets UL 94 V-0 flammability rating,RoHS-compliant
- Terminals: Tin plated leads, solderable per J-STD-002 and . JESD22-B102
- Polarity: Color Band denotes cathode end

Maximum Ratings (Ta=25°C Unless otherwise specified)

| PARAMETER | Symbol | Unit | Conditions | | MBR10-F | | | | | | | |
|--|------------------|------|--|------------|---------|----|----|----|-----|-----|--|--|
| | | | | | 45 | 50 | 60 | 90 | 100 | 150 | | |
| Repetitive Peak Reverse Voltage | V _{RRM} | V | | 35 | 45 | 50 | 60 | 90 | 100 | 150 | | |
| Average Rectified Output Current | lo | Δ | 60HZ Half-sine wave, Resistance load, Tc(Fig.1) | 10.0 | | | | | | | | |
| Surge(Nonrepetitive)Forward Current | I _{FSM} | А | 60HZ sine wave, 1 cycle, Ta=25℃ | 150 | | | | | | | | |
| Storage Temperature | T _{stg} | °C | | -55 ~ +150 | | | | | | | | |
| Junction Temperature | Tj | °C | | -55 ~ +150 | | | | | | | | |

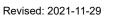
Electrical Characteristics (Ta=25°C Unless otherwise specified)

| PARAMETER | Symbol | Unit | Conditions | | | MBR10-F | | | | | | | |
|----------------------|-------------------|------|-----------------------------------|-----------------|-----|-----------|-------------------|------|----|------|-----|--|--|
| PARAIVIETER | Symbol | | Conditions | | 35 | 45 | 50 | 60 | 90 | 100 | 150 | | |
| Peak Forward Voltage | V _{FM} | V | I _{FM} =10A | | | 0.70 0.80 | | 0.85 | | 1.05 | | | |
| Peak Reverse Current | I _{RRM1} | - mA | V _{RM} =V _{RRM} | Ta=25 ℃ | 0.1 | | | | | | | | |
| | I _{RRM2} | | VRM-VRRM | Ta=125 ℃ | | 15 10 | | 6.0 | |) | | | |
| Thermal Resistance | R _{0J-C} | °C/W | Between junction and case | | | | 3.0 ¹⁾ | | | | | | |

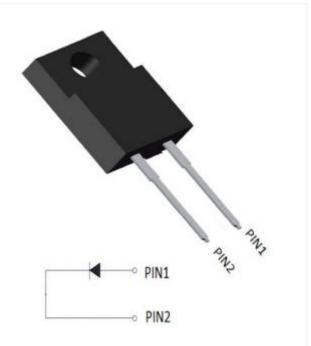
NOTES:

¹⁾Thermal resistance from junction to case per leg with heat-sink size of 2"x3"x0.25"A-L plate





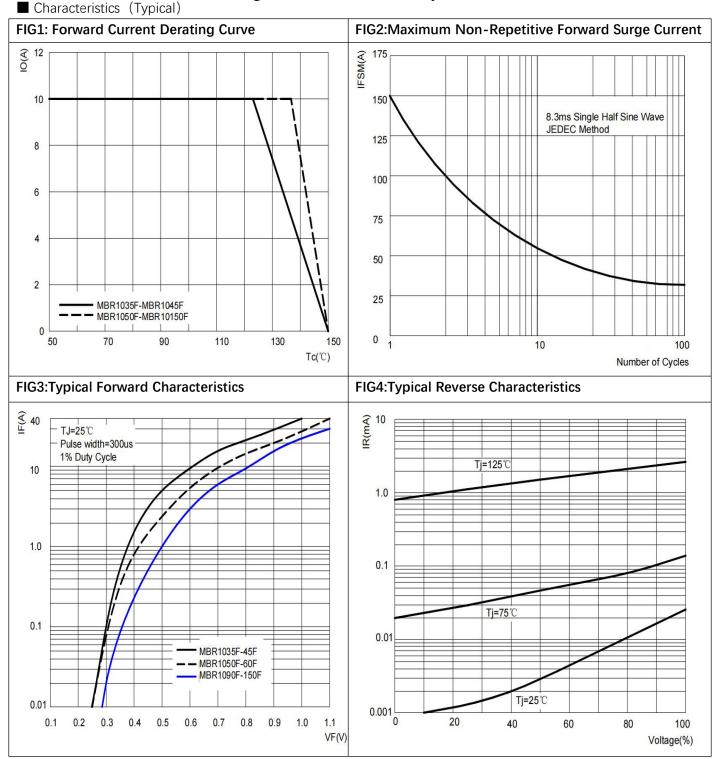






MBR1035F THRU MBR10150F

High Performance Schottky Diodes











MBR1035F THRU MBR10150F High Performance Schottky Diodes

Ordering Information (Example)

| PREFERED | PACKAGE CODE | MINIMUM PACKAGE(pcs) | INNER BOX QUANTITY(pcs) | OUTER CARTON QUANTITY(pcs) | DELIVERY MODE | |
|---------------------|-----------------|-------------------------|----------------------------|-------------------------------|---------------|--|
| MBR1035F ~MBR10150F | ITO-220AC | 50 | 1000 | 5000 | Tube | |

Outline Dimensions

